

DialogIP

EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE

Publication Number: 2001-226561 (JP 2001226561 A) , August 21, 2001

Inventors:

- YAGISAWA TAKASHI

Applicants

- SUMITOMO BAKELITE CO LTD

Application Number: 11-353024 (JP 99353024) , December 13, 1999

Priority:

- 11-349634 [JP 99349634], JP (Japan), December 09, 1999

International Class:

- C08L-063/00
- C08K-003/22
- H01L-023/29
- H01L-023/31

Abstract:

PROBLEM TO BE SOLVED: To obtain an epoxy resin composition for sealing a semiconductor which does not contain a halogen-containing flame-retardant and an antimony compound and is excellent in molding properties, flame retardancy, high temperature storage characteristics, moisture resistance reliability and solder crack resistance. **SOLUTION:** The epoxy resin composition for sealing a semiconductor comprises, as essential ingredients, (A) an epoxy resin, (B) a phenolic resin, (C) a curing accelerator, (D) an inorganic filler and (E) a metal hydroxide solid solution represented by the general formula: $Mg_{1-x}M2_x(OH)_2$ (wherein $M2^+$ is at least one divalent metal ion selected from the group consisting of Mn^{2+} , Fe^{2+} , Co^{2+} , Ni^{2+} , Cu^{2+} and Zn^{2+} ; and (x) is a number of $0.01 \leq x \leq 0.5$), and the specific surface area of the metal hydroxide solid solution represented by the general formula is 1.5-4.5 m²/g. **COPYRIGHT:** (C)2001,JPO

JAPIO

© 2004 Japan Patent Information Organization. All rights reserved.
Dialog® File Number 347 Accession Number 6998961